

Claims:

- 1 1. An integrated circuit comprising:
 - 2 a wafer having circuitry disposed thereon;
 - 3 a plurality of conductors coupled to the wafer;
 - 4 a structure that encapsulates and supports the wafer; and
 - 5 magnetic material disposed to alter an inductance associated with at least one
 - 6 of the plurality of conductors.

- 1 2. The integrated circuit of claim 1, wherein the magnetic material is at least
- 2 partially disposed within the structure.

- 1 3. The integrated circuit of claim 1, wherein the magnetic material is substantially
- 2 homogeneously disposed throughout the structure.

- 1 4. The integrated circuit of claim 1, wherein at least a portion of the magnetic
- 2 material is disposed external to the structure.

- 1 5. The integrated circuit of claim 1, wherein the magnetic material comprises a
- 2 ferromagnetic material.

- 1 6. The integrated circuit of claim 1, wherein the magnetic material comprises a
- 2 ferrite material.

- 1 7. The integrated circuit of claim 1, further comprising at least one choke structure
- 2 formed of the magnetic material, wherein each choke structure associates with at
- 3 least one respective conductor of the plurality of conductors.

- 1 8. The integrated circuit of claim 1, wherein the magnetic material forms a plurality
- 2 of choke structures, each of the choke structures being associated with at least
- 3 one respective conductor of the plurality of conductors

- 1 9. The integrated circuit of claim 7, wherein the structure comprises a dielectric
- 2 material encapsulating at least a portion of the choke structures.

- 1 10. The integrated circuit of claim 7, wherein at least some of the choke structures
- 2 are disposed external to the structure.